

Product / Process Change Notification



N° 2017-075-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of Infineon Kulim, Malaysia as an additional wafer test location affecting dedicated products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **10. November 2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► Products affected:

Sales Name	SP N°	OPN	Package
TLE6365G	SP000317609	TLE6365GXUMA1	PG-DSO-8
TLE6368G2	SP000656590	TLE6368G2AUMA1	PG-DSO-36
TLE6711G	SP000317613	TLE6711GXUMA1	PG-DSO-14
TLE6711GL	SP001128372	TLE6711GLXUMA2	PG-DSO-20

► Detailed Change Information:

Subject: Introduction of Infineon Kulim, Malaysia as an additional wafer test location affecting dedicated products.

Reason: To continuously ensure the delivery capability to our customers, the wafer test capacity will be extended.

Description:

Old

- Infineon Technologies Austria AG, Villach, Austria

New

- Infineon Technologies Austria AG, Villach, Austria
- or*
- Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia

► Product Identification:

Traceability is ensured by lot number.

► Impact of Change:

No change in form, fit, or function and no impact on quality and reliability of the final product.
No change of SP number or OPN.
The wafer test location verification is performed via the Advanced Measurement System Analysis (AMSA) methodology.

► Attachments:

n.a.

► Time Schedule:

- | | |
|-------------------------------|----------------------|
| ■ Final qualification report: | Available on request |
| ■ First samples available: | n.a. |
| ■ Intended start of delivery: | 2018-10-01 |

If you have any questions, please do not hesitate to contact your local Sales office.